

General Description

The WSP9936 is the highest performance trench N-ch MOSFET with extreme high cell density, which provide excellent R_{DS(on)} and gate charge for most of the small power switching and load switch applications.

The WSP9936 meet the RoHS and Green Product requirement with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent C_{dv/dt} effect decline
- Green Device Available

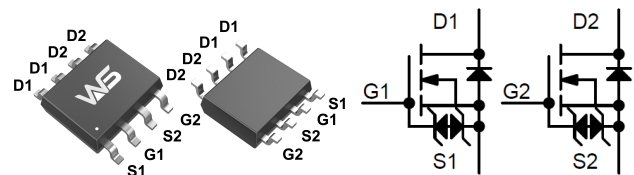
Product Summary

| BVDSS | R _{DS(on)} | I _D |
|-------|---------------------|----------------|
| 20V | 14mΩ | 8A |

Applications

- High Frequency Point-of-Load Synchronous
Small power switching for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- ESD:2KV

SOP-8 Pin Configuration



Absolute Maximum Ratings

| Symbol | Parameter | Rating | Units |
|-----------------------------------|---|------------|-------|
| V _{DS} | Drain-Source Voltage | 20 | V |
| V _{GS} | Gate-Source Voltage | ± 12 | V |
| I _{D@T_A=25°C} | Continuous Drain Current, V _{GS} @ 4.5V ¹ | 8 | A |
| I _{D@T_A=70°C} | Continuous Drain Current, V _{GS} @ 4.5V ¹ | 6.1 | A |
| I _{DM} | Pulsed Drain Current ² | 40 | A |
| P _{D@T_A=25°C} | Total Power Dissipation ³ | 2 | W |
| T _{STG} | Storage Temperature Range | -55 to 150 | °C |
| T _J | Operating Junction Temperature Range | -55 to 150 | °C |

Thermal Data

| Symbol | Parameter | Typ. | Max. | Unit |
|------------------|--|------|------|------|
| R _{θJA} | Thermal Resistance Junction-ambient ¹ | --- | 62.5 | °C/W |
| R _{θJC} | Thermal Resistance Junction-Case ¹ | --- | 10 | °C/W |

Electrical Characteristics (T_J=25 °C, unless otherwise noted)

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|-------------------------------------|--|---|------|-------|------|-------|
| BV _{DSS} | Drain-Source Breakdown Voltage | V _{GS} =0V, I _D =250uA | 20 | --- | --- | V |
| ΔBV _{DSS} /ΔT _J | BVDSS Temperature Coefficient | Reference to 25°C, I _D =1mA | --- | 0.022 | --- | V/°C |
| R _{DS(ON)} | Static Drain-Source On-Resistance ² | V _{GS} =4.5V, I _D =8A | --- | 15 | 26 | mΩ |
| | | V _{GS} =2.5V, I _D =6.8A | --- | 19 | 34 | |
| V _{GS(th)} | Gate Threshold Voltage | V _{GS} =V _{DS} , I _D =250uA | 0.5 | 0.75 | 1.1 | V |
| ΔV _{GS(th)} | V _{GS(th)} Temperature Coefficient | | --- | -2.33 | --- | mV/°C |
| I _{DSS} | Drain-Source Leakage Current | V _{DS} =16V, V _{GS} =0V, T _J =25°C | --- | --- | 1 | uA |
| | | V _{DS} =16V, V _{GS} =0V, T _J =55°C | --- | --- | 5 | |
| I _{GSS} | Gate-Source Leakage Current | V _{GS} =±12V, V _{DS} =0V | --- | --- | ±100 | nA |
| g _{fs} | Forward Transconductance | V _{DS} =5V, I _D =5A | --- | 25 | --- | S |
| R _g | Gate Resistance | V _{DS} =0V, V _{GS} =0V, f=1MHz | --- | 4.5 | --- | Ω |
| Q _g | Total Gate Charge (4.5V) | V _{DS} =10V, V _{GS} =4.5V, I _D =8A | --- | 15.6 | 17 | nC |
| Q _{gs} | Gate-Source Charge | | --- | 1.3 | --- | |
| Q _{gd} | Gate-Drain Charge | | --- | 2.5 | --- | |
| T _{d(on)} | Turn-On Delay Time | V _{DD} =10V, V _{GS} =4.5V, R _G =6Ω I _D =5A, R _L =10Ω. | --- | 4 | 9.5 | ns |
| T _r | Rise Time | | --- | 6 | 24 | |
| T _{d(off)} | Turn-Off Delay Time | | --- | 25 | 73 | |
| T _f | Fall Time | | --- | 4 | 39 | |
| C _{iss} | Input Capacitance | V _{DS} =10V, V _{GS} =0V, f=1MHz | --- | 520 | --- | pF |
| C _{oss} | Output Capacitance | | --- | 105 | --- | |
| C _{rss} | Reverse Transfer Capacitance | | --- | 60 | --- | |

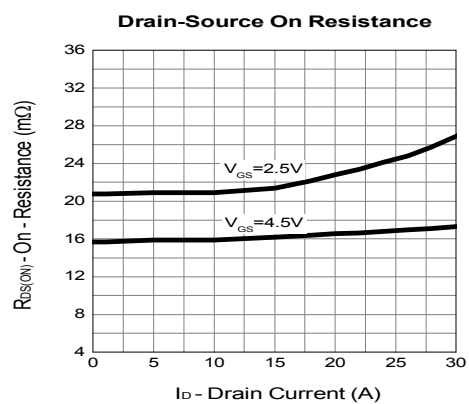
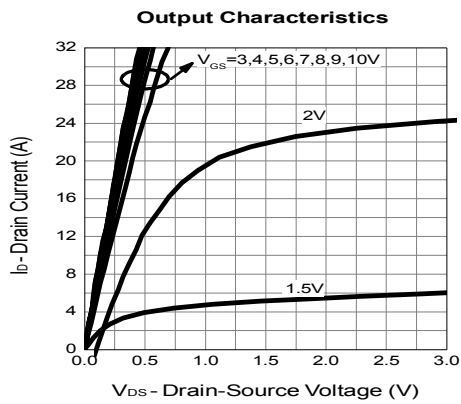
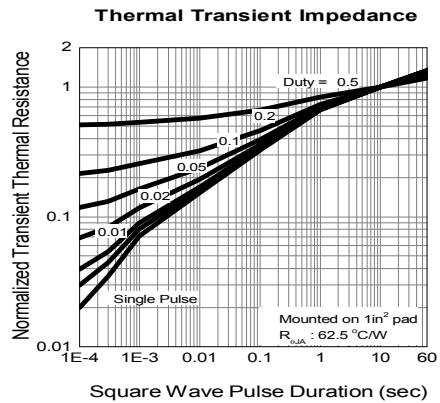
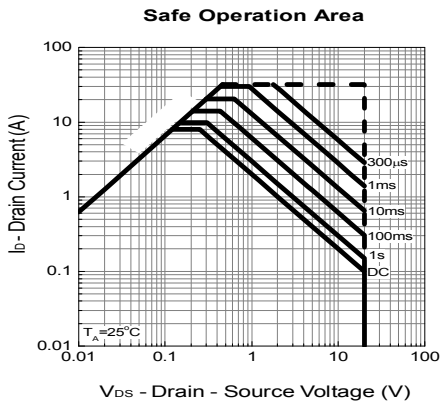
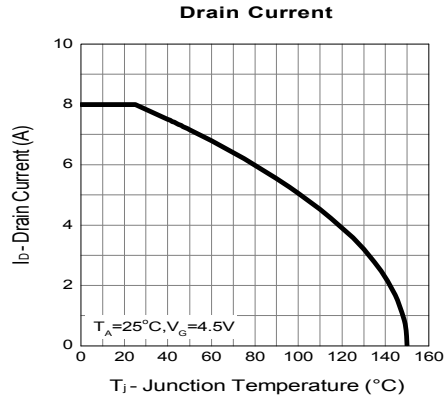
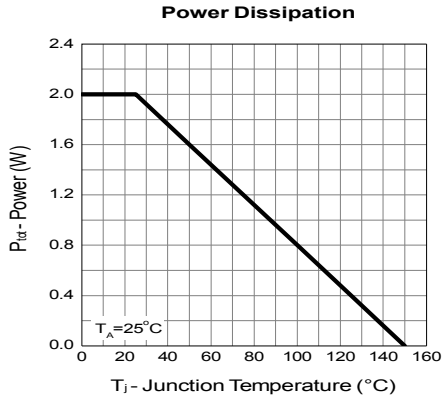
Diode Characteristics

| Symbol | Parameter | Conditions | Min. | Typ. | Max. | Unit |
|-----------------|--|---|------|------|------|------|
| I _S | Continuous Source Current ^{1,4} | V _G =V _D =0V, Force Current | --- | --- | 3.7 | A |
| I _{SM} | Pulsed Source Current ^{2,4} | | --- | --- | 40 | A |
| V _{SD} | Diode Forward Voltage ² | V _{GS} =0V, I _S =1A, T _J =25°C | --- | --- | 1.3 | V |
| t _{rr} | Reverse Recovery Time | I _F =8A, di/dt=100A/μs, T _J =25°C | --- | 19.2 | --- | nS |
| Q _{rr} | Reverse Recovery Charge | | --- | 4.6 | --- | nC |

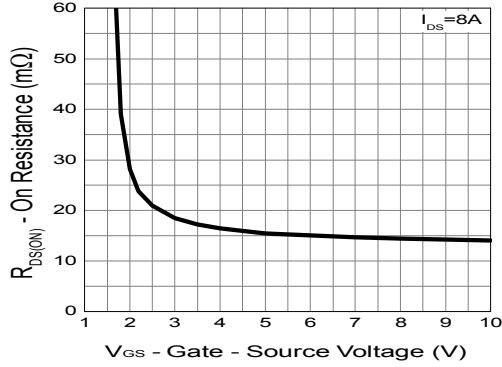
Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper,t<10sec.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3.The power dissipation is limited by 150°C junction temperature
- 4.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

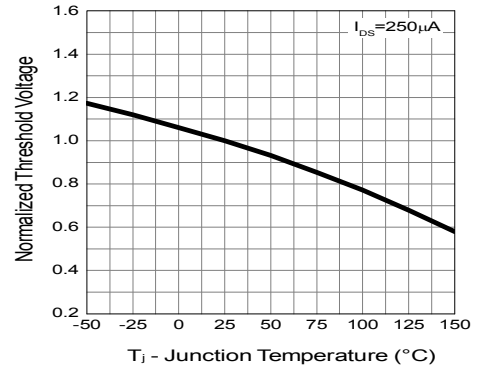
Typical Characteristics



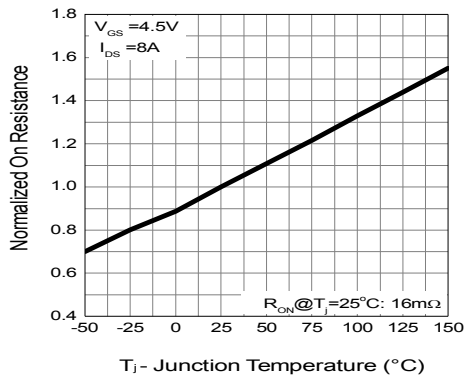
Transfer Characteristics



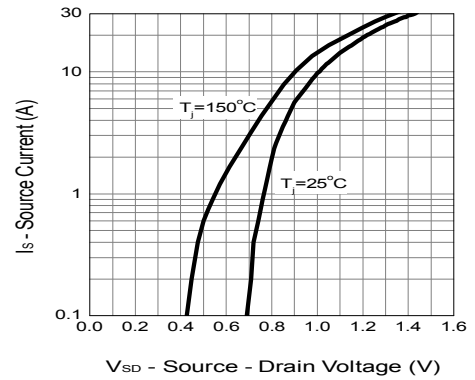
Gate Threshold Voltage



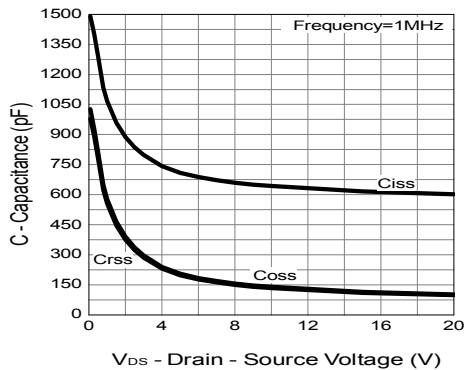
Drain-Source On Resistance



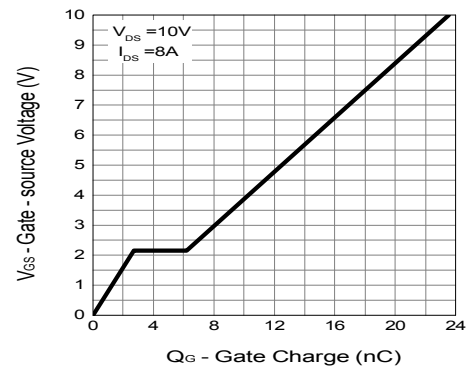
Source-Drain Diode Forward



Capacitance



Gate Charge





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